

X 500 Specifications

Model	x500
Build platform* (XxYxZ)	500 x 400 x 450 mm / 19.7 x 15.7 x 17.7 in
Print speed	10 - 150 mm/s
Travel speed	10 - 300 mm/s
Layer heigh (min.)	0,02 mm
Filament diameter (standard)	1,75 mm
Nozzle	0,4 Ø mm (opt.: 0,25 / 0,30 / 0,5 / 0,6 / 0,8)
Material	German RepRap Material Variety
	Depending on the application, as well as on size and geometry, a wide range of materials is available.
Extruder type	DD4 Dual
Extruder temperature (max.)	400° / 752 °F
Print bed technology	heatable
File transfer	Stand-Alone Printing with Touch Display, USB, Ethernet, WLAN optionally
Software	Simplify3D Software
Operating voltage	110 / 230 V
Ambient temperature	15-26°C / 59 – 78.8°F
Dimensions approx. (WxDxH)	1120 x 850 x 955 mm / 44 x 33.5 x 37.6 in
Weight approx.	185 kg / 408 lbs
Options	Maintenance Contract
Heated Building Chamber	80° / 176 °F
Heat Bed (max.)	120° / 248 °F
Technology	FFF (Fused Filament Fabrication)
* Depends on the configuration	